

# PATENT ABSTRACTS OF JAPAN

(11) Publication number : **55-053447**  
 (43) Date of publication of application : **18.04.1980**

(51) Int. Cl. :  
**H01L 23/04**  
**H01L 29/78**

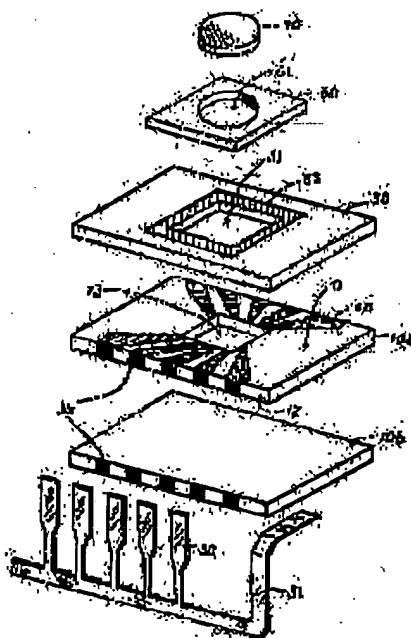
(21) Application number : **53-127101** (71) Applicant : **FUJITSU LTD**  
 (22) Date of filing : **16.10.1978** (72) Inventor : **AOKI EIJI**

**(54) SEMICONDUCTOR PACKAGE OF ULTRAVIOLET RAY TRANSMITTING TYPE**

**(57) Abstract:**

**PURPOSE:** To obtain a package of ultraviolet ray permeating type which can be manufactured easily and which has a high elimination factor for ultraviolet ray, and of construction of superior airtightness.

**CONSTITUTION:** A plate 10a with a hole 13, a plate 10b and a frame 50 with a hole 51 are made out of a ceramic sheet. A printed conductive circuit is provided on the upper side and the flank of the plate 10a, which is piled on the frame 50, and the plate and the frame are pressed together with a thin ceramic paste sandwiched between them. After three laminated plates are sintered, the edge of the circuit 40 is plated with Au, etc., then an external lead 30 with a frame 31 are attached to the flank of a package, using wax 35. Next the lead portion attached to the package is covered by Au plating, before being contained in a semiconductor chip and the package, then wired. A ceramic plate with a circular opening 61 is made, and ultraviolet transmitting glass 70 having a relatively smaller diameter is inserted through the opening 61. The glass is fixed to the hole by heating, and a cap 60 is attached to the frame 50 through a glued layer 55. The cap 60 is semi-transparent body made by adding a substance of MgO series to Al2O3. Thus an extremely suitable package of ultraviolet ray transmitting type can be obtained.



**LEGAL STATUS**

[Date of request for examination]

[Date of sending the examiner's decision of rejection]

[Kind of final disposal of application other than the examiner's decision of rejection or application converted registration]

[Date of final disposal for application]

[Patent number]

[Date of registration]

[Number of appeal against examiner's decision of rejection]

[Date of requesting appeal against examiner's decision of rejection]